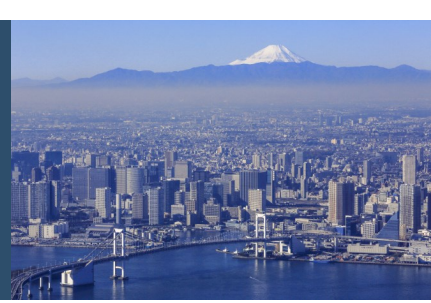


3rd Annual Tokyo SOI Workshop

May 31st - June 1st 2017

Yokohama Landmark Tower - Takeda Hall, Tokyo University



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FDSOI Ecosystem and Reception

May 31st, 2017 @ Yokohama Landmark Tower 25F

1.00 - 2.00 p.m.

REGISTRATION

2.00 - 5.30 p.m.

FDSOI Ecosystem

2.00 – 2.30pm

TCAD, EDA and IP to support FDSOI

David Dutton, CEO Silvaco

2.30 – 3.00pm

FDX™ (FD-SOI) goes Mainstream

Gregg Bartlett, SVP GlobalFoundries

3.00 – 3.30pm

INVECAS IP Portfolio in 22FDX

Bhaskar Kollo, Sr. Director Business Development and Customer Engineering, Invecas

3.30 – 4.00pm

FDSOI : a Low Power, High Performance Technology Scalable Down to 10nm

Laurent Grenouillet, Expert, CMOS & Memory Integration ,CEA-Leti

4.00 - 4.30 p.m.

COFFEE BREAK

4.30 – 5.00pm

I-fuse(tm): the best OTP of choice for FD-SOI and sub-14nm nodes

Shine Chung, Chairman, Attopsemi Technology

5.00 – 5.30pm

Product Design Methodology

Christophe Tretz, SOI Consortium

5.30 – 8.00pm

NETWORKING RECEPTION

ORGANIZER



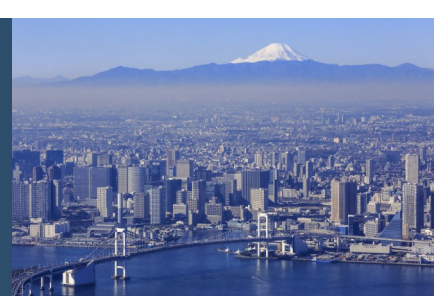
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Convergence of IoT, Automotive through Connectivity

June 1st, 2017 @ Takeda Hall, Tokyo University, Tokyo

08.30 - 9.20 a.m.

REGISTRATION

09.20 - 9.30 a.m.

WELCOME

Carlos Mazure, Executive Director, SOI Industry Consortium

09.30 - 10.30 a.m.

ULTRA LOW POWER APPLICATIONS

09.30 – 10.00am

Kenichi Nakano, General Manager, Sony IoT

10.00 – 10.30am

Value added FD-SOI technology to be major player in IoT, automotive, and connectivity

Yongjoo Jeon, Principal Designer in Foundry Marketing, Samsung

10.30 - 11.00 a.m.

NETWORKING BREAK

11.00 - 12.30 a.m.

TECHNOLOGIES FOR AUTOMOTIVE

11.00 – 11.30am

LIDARs and sensor fusion ECUs advancing ADAS architectures towards automated driving

Akhilesh Kona, Senior Analyst, IHS Markit

11.30 – 12.00pm

MIPS leading heterogeneous compute in Automotive & IoT

Steven Yeung, Design Manager, MIPS, Imagination Technologies

12.00 – 12.30pm

Future of Automotive Industry - Road is Paved with SOI

Vincent Roger, Corporate Business Developer in Northern Europe, CEA-Leti

12.30 - 1.30 p.m.

LUNCH

01.30 - 3.30 p.m.

IoT – CONNECTIVITY—INFRASTRUCTURE

01.30 – 02.00pm

Enabling An Interconnected Digital World

Jonathan Smith, Director Cadence

02.00 – 02.30pm

Nokia Future X Network for 5G and IoT

Brian Cho, Head of Technology for APAC & Japan, Nokia,

02.30 – 03.00pm

Delivering on the Promises of 5G: Semiconductor Solutions for the Next Wave of Data

Peter Rabbeni, Senior Director, GlobalFoundries on 5G

03.00 – 03.30pm

Sensor-to-Cloud Connectivity Solution for IoT,

Hiroshi Noguchi, Director of AMG Product Marketing, STMicroelectronics Japan



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03.30 - 4.00p.m. NETWORKING BREAK

04.00 - 5.30p.m. SUPPLY CHAIN

04.00 – 04.30pm **Enabling SOI and IoT: An Equipment and Materials Engineering Perspective**
Sesh Ramaswami, Managing Director, Applied Materials

04.30 – 05.00pm **SCREEN Equipment Manufacturer: Full participation within the SOI Consortium**
Hirofumi Uchida, Senior VP, Screen

05.00 – 05.30pm **Role of Substrate in Accelerating Mass Adoption of SOI Technologies**
Thomas Pilisczuck, EVP, Soitec

05.30 - 5.40p.m. CLOSING REMARKS
Giorgio Cesana, Executive Co-Director, SOI Industry Consortium